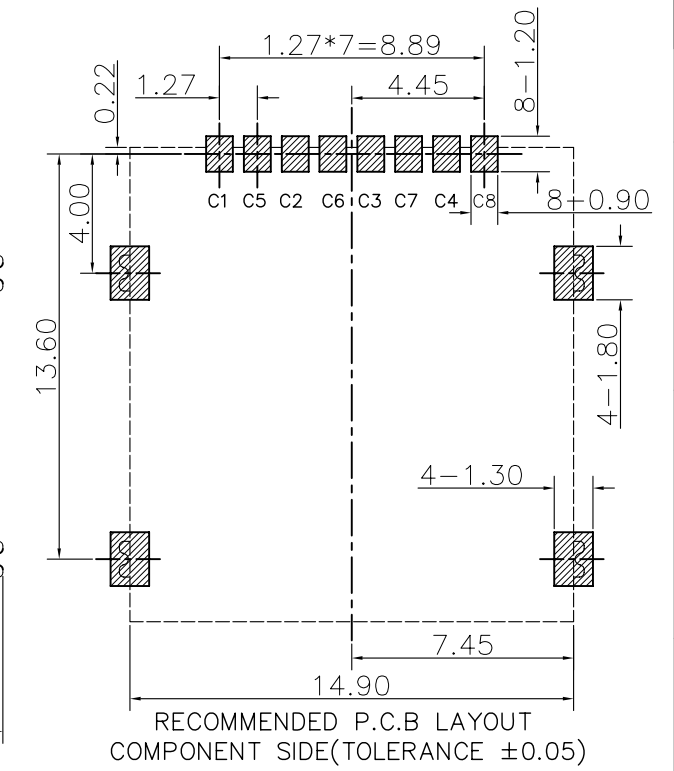
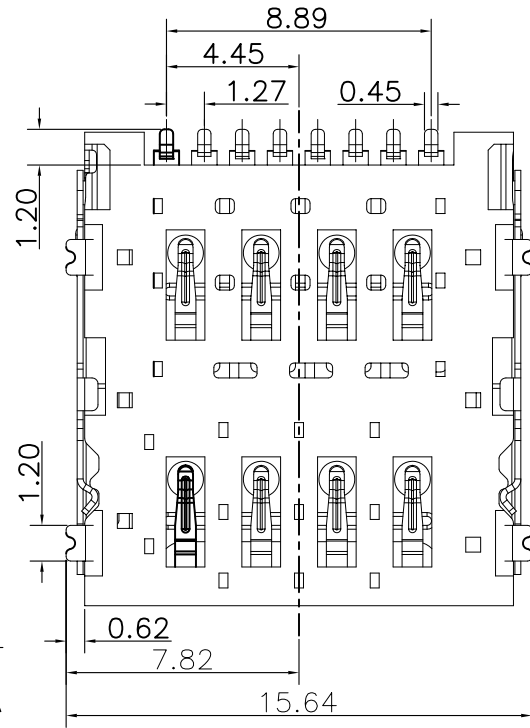
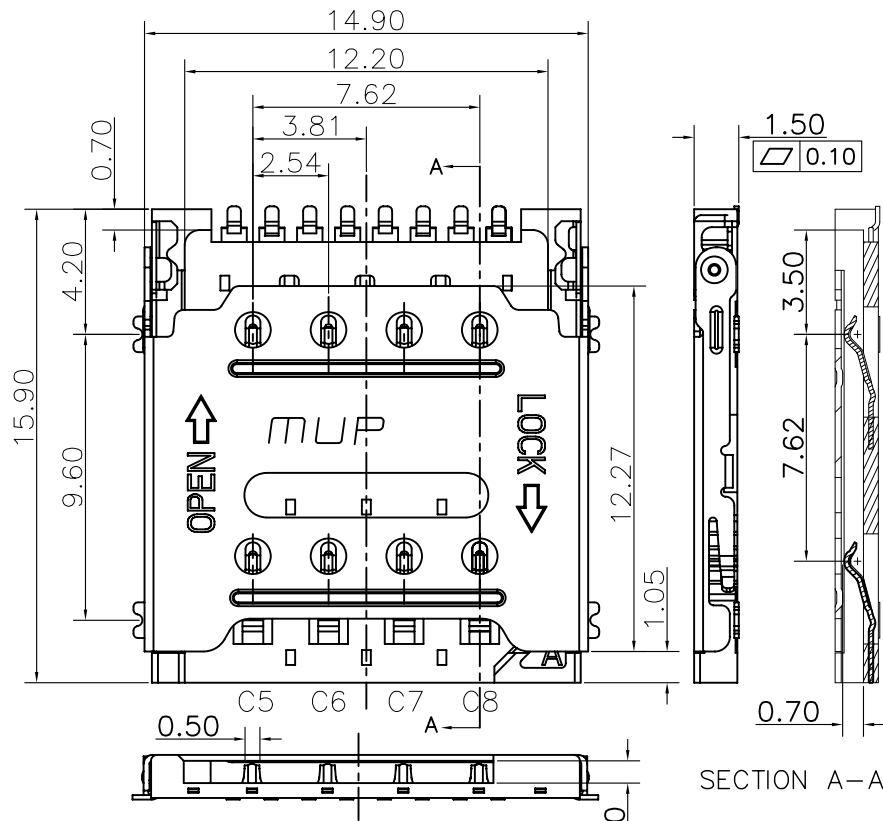


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 15.90LX14.90WX1.50H mm
 Weight: Approx 0.53±0.2g
 Durability: 5,000 cycles min.

2.Electrical Characteristics

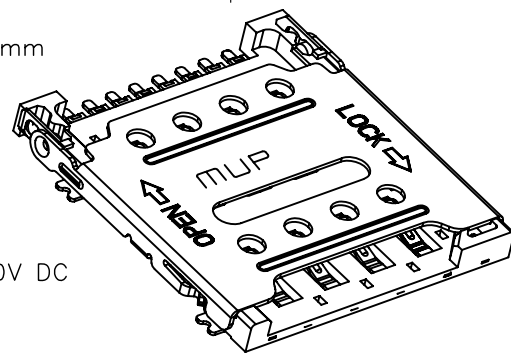
Contact resistance: 50mΩ typical,
 100mΩ max
 Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vaporphase: 215°C,30sec.Max
 IR reflow: 250°C,5sec.Max
 Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C
 Operating humidity: 10%~+95%RH



Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

MUP[®] MUP INDUSTRIAL CO.,LTD.

NAME: **Micro-SIM Card Connector**
 MODEL NO: **MUP-C791 TYPE2**
 TYPE: **Hinge Type,8 PIN,H1.50mm**

PROJ.	UNIT	SCALE	DRAWN	DWG NO.:
①	mm	1:1	CHECKED	DWG-MUP-C791-002
CUSTOMER DRAWING			APPROVAL	SHEET
				1/1
				REVISION
				X1

